

ABSOLUTE MAXIMUM RATINGS

Supply Voltage (V_{CC}) 7V
 Input Voltage
 Logic Inputs $-0.3V$ to $V_{CC} + 0.3V$
 Receiver Inputs $\pm 15V$
 Driver Output Voltage (Forced) $\pm 15V$

Driver Short-Circuit Duration Indefinite
 Operating Temperature Range $0^{\circ}C$ to $70^{\circ}C$
 Storage Temperature Range $-65^{\circ}C$ to $150^{\circ}C$
 Lead Temperature (Soldering, 10 sec) $300^{\circ}C$

PACKAGE/ORDER INFORMATION

TOP VIEW G PACKAGE 28-LEAD PLASTIC SSOP $T_{JMAX} = 150^{\circ}C$, $\theta_{JA} = 96^{\circ}C/W$	ORDER PART NUMBER LTC1323CG	TOP VIEW S PACKAGE 16-LEAD PLASTIC SO $T_{JMAX} = 125^{\circ}C$, $\theta_{JA} = 85^{\circ}C/W$	ORDER PART NUMBER LTC1323CS
TOP VIEW SW PACKAGE 24-LEAD PLASTIC SO WIDE $T_{JMAX} = 125^{\circ}C$, $\theta_{JA} = 85^{\circ}C/W$	ORDER PART NUMBER LTC1323CSW		

Consult factory for Industrial and Military grade parts.

ELECTRICAL CHARACTERISTICS $V_{CC} = 5V \pm 10\%$, $T_A = 0^\circ C$ to $70^\circ C$ (Notes 2, 3)

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Supplies							
I_{CC}	Normal Operation Supply Current	No Load, SHDN = 0V, $\overline{CPEN} = 0V$, $\overline{TXDEN} = 0V$, $\overline{RXEN} = 0V$	●		2.4	4	mA
	Receiver Keep-Alive Supply Current	No Load, SHDN = 0V, $\overline{CPEN} = V_{CC}$, $\overline{TXDEN} = 0V$, $\overline{RXEN} = 0V$	●		65	100	μA
	Shutdown Supply Current	No Load, SHDN = V_{CC} , $\overline{CPEN} = X$, $\overline{TXDEN} = X$, $\overline{RXEN} = 0V$	●		0.5	10	μA
V_{EE}	Negative Supply Output Voltage	$I_{LOAD} \leq 10mA$ (Note 4), $V_{CC} = 5V$, $R_L = 100\Omega$ (Figure 1), $TXI = V_{CC}$, $R_{TXO} = 3k$ (Figure 5)	●	-5.5	-5	-4.5	V
f_{OSC}	Charge Pump Oscillator Frequency				200		kHz
Differential Driver							
V_{OD}	Differential Output Voltage	No Load $R_L = 100\Omega$ (Figure 1)	● ●	± 8 ± 2			V
ΔV_{OD}	Change in Magnitude of Differential Output Voltage	$R_L = 100\Omega$ (Figure 1)			0.2		V
Differential Driver							
V_{OC}	Differential Common-Mode Output Voltage	$R_L = 100\Omega$			3		V
V_{OS}	Single-Ended Output Voltage	No Load $R_L = 3k$ to GND	● ●	± 4.0 ± 3.7			V V
V_{CMR}	Common-Mode Range	SHDN = V_{CC} or $\overline{CPEN} = V_{CC}$ or Power Off	●			± 10	V
I_{SS}	Short-Circuit Current	$-5V \leq V_O \leq 5V$	●	35	120	500	mA
I_{OZ}	Three-State Output Current	SHDN = V_{CC} or $\overline{CPEN} = V_{CC}$ or Power Off, $-10V \leq V_O \leq 10V$	●		± 2	± 200	μA
Single-Ended Driver (Note 5)							
V_{OS}	Single-Ended Output Voltage	No Load $R_L = 3k$ to GND	● ●	± 4.5 ± 3.7			V V
V_{CMR}	Common-Mode Range	SHDN = V_{CC} or $\overline{CPEN} = V_{CC}$ or $\overline{TXDEN} = V_{CC}$ or Power Off	●			± 10	V
I_{SS}	Short-Circuit Current	$-5V \leq V_O \leq 5V$	●	35	220	500	mA
I_{OZ}	Three-State Output Current	SHDN = V_{CC} or $\overline{CPEN} = V_{CC}$ or $\overline{TXDEN} = V_{CC}$ or Power Off, $-10V \leq V_O \leq 10V$	●		± 2	± 200	μA
Receivers							
R_{IN}	Input Resistance	$-7V \leq V_{IN} \leq 7V$	●	12			k Ω
	Differential Receiver Threshold Voltage	$-7V \leq V_{CM} \leq 7V$	●	-200		200	mV
	Differential Receiver Input Hysteresis	$-7V \leq V_{CM} \leq 7V$	●		70		mV
	Single-Ended Input, Low Voltage	(Note 5)	●			0.8	V
	Single-Ended Input, High Voltage	(Note 5)	●	2			V
V_{OH}	Output High Voltage	$I_O = -4mA$	●	3.5			V
V_{OL}	Output Low Voltage	$I_O = 4mA$	●			0.4	V
I_{SS}	Output Short-Circuit Current	$-5V \leq V_O \leq 5V$	●	7		85	mA
I_{OZ}	Output Three-State Current	$-5V \leq V_O \leq 5V$, $\overline{RXEN} = V_{CC}$	●		± 2	± 100	μA

ELECTRICAL CHARACTERISTICS $V_{CC} = 5V \pm 10\%$, $T_A = 0^\circ C$ to $70^\circ C$ (Notes 2 and 3)

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Logic Inputs							
V_{IH}	Input High Voltage	All Logic Input Pins	●	2.0			V
V_{IL}	Input Low Voltage	All Logic Input Pins	●			0.8	V
I_C	Input Current	All Logic Input Pins	●		± 1.0	± 20	μA
Switching Characteristics							
t_{PLH}, t_{PHL}	Differential Driver Propagation Delay	$R_L = 100\Omega$, $C_L = 100pF$ (Figures 2, 7)	●		40	120	ns
	Differential Driver Propagation Delay with Single-Ended Load	$R_L = 3k$, $C_L = 100pF$ (Figures 3, 9)	●		120	180	ns
	Single-Ended Driver Propagation Delay	$R_L = 3k$, $C_L = 100pF$, (Figures 5, 10) (Note 5)	●		40	120	ns
	Differential Receiver Propagation Delay	$C_L = 15pF$ (Figures 2, 11)	●		70	160	ns
	Single-Ended Receiver Propagation Delay	$C_L = 15pF$ (Figures 6, 12) (Note 5)	●		70	160	ns
	Inverting Receiver Propagation Delay in Keep-Alive Mode, $SHDN = 0V$, $\overline{CPEN} = V_{CC}$	$C_L = 15pF$ (Figures 6, 12) (Note 5)	●		150	600	ns
t_{SKEW}	Differential Driver Output to Output	$R_L = 100\Omega$, $C_L = 100pF$ (Figures 2, 7)	●		10	50	ns
t_r, t_f	Differential Driver Rise/Fall Time	$R_L = 100\Omega$, $C_L = 100pF$ (Figures 2, 7)	●		50	150	ns
	Differential Driver Rise/Fall Time with Single-Ended Load	$R_L = 3k$, $C_L = 100pF$ (Figures 3, 9)	●		50	150	ns
	Single-Ended Driver Rise/Fall Time	$R_L = 3k$, $C_L = 100pF$ (Figures 5, 10) (Note 5)	●		15	80	ns
t_{HDIS}, t_{LDIS}	Differential Driver Output Active to Disable	$C_L = 15pF$ (Figures 4, 8)	●		180	250	ns
	Any Receiver Output Active to Disable	$C_L = 15pF$ (Figures 4, 13)	●		30	100	ns
t_{ENH}, t_{ENL}	Differential Driver Enable to Output Active	$C_L = 15pF$ (Figures 4, 8)	●		180	250	ns
	Any Receiver, Enable to Output Active	$C_L = 15pF$ (Figures 4, 13)	●		30	100	ns
V_{EER}	Supply Rise Time from Shutdown or Receiver Keep-Alive	$C1 = C2 = 0.33\mu F$, $C_{VEE} = 1\mu F$	●		0.2		ms

The ● denotes specifications which apply over the full operating temperature range.

Note 1: Absolute maximum ratings are those values beyond which the life of a device may be impaired.

Note 2: All currents into device pins are positive; all currents out of device pins are negative. All voltages are referenced to ground unless otherwise specified.

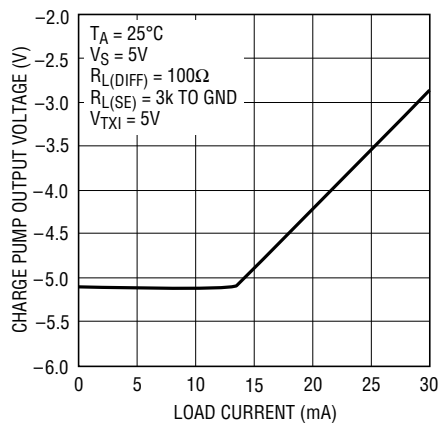
Note 3: All typicals are given at $V_{CC} = 5V$, $T_A = 25^\circ C$.

Note 4: I_{LOAD} is an external current being sunk into the V_{EE} pin.

Note 5: These specifications apply to the 24-pin SO Wide package only.

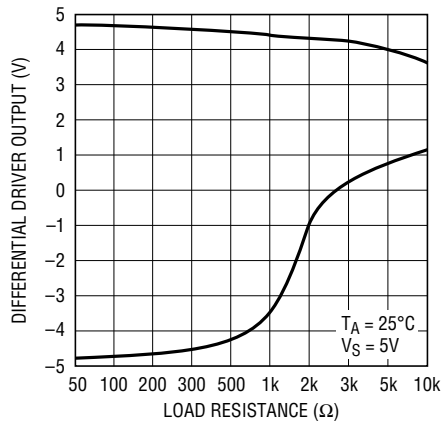
TYPICAL PERFORMANCE CHARACTERISTICS

**Charge Pump Output Voltage
vs Load Current**



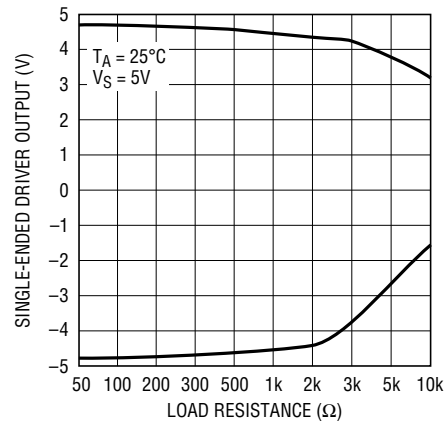
LTC1323 • TPC01

**Differential Driver Swing
vs Load Resistance**



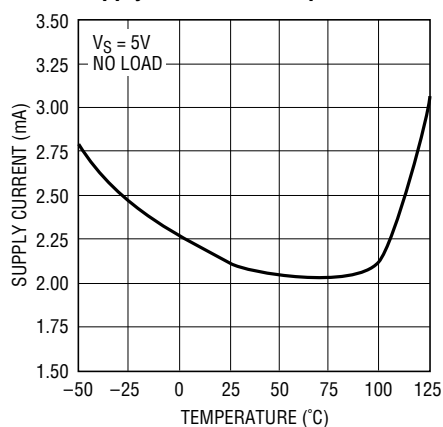
LTC1323 • TPC02

**Single-Ended Driver Swing
vs Load Resistance**



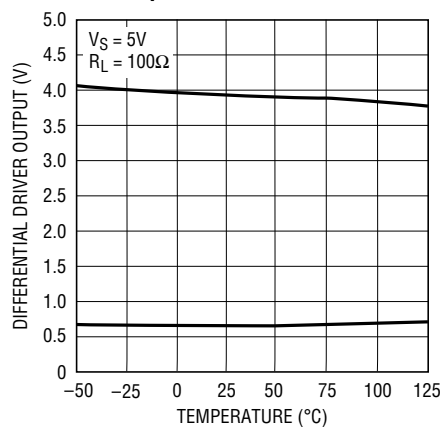
LTC1323 • TPC03

Supply Current vs Temperature



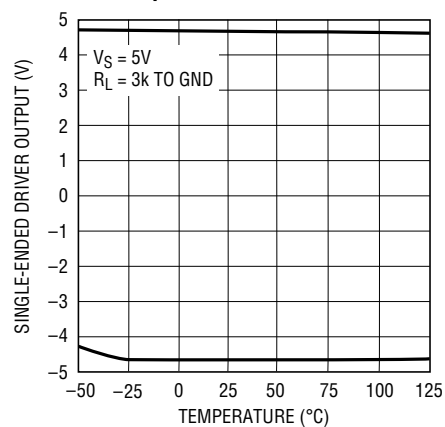
LTC1323 • TPC04

**Differential Driver Swing
vs Temperature**



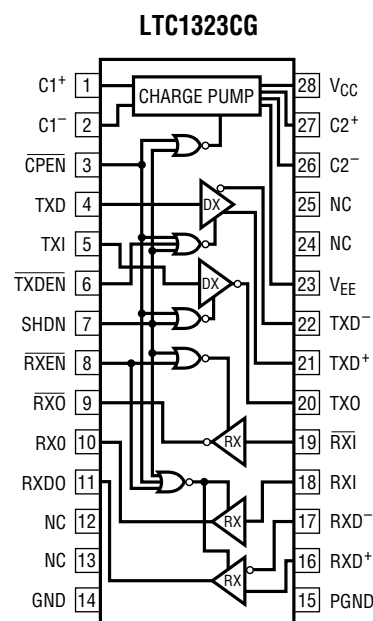
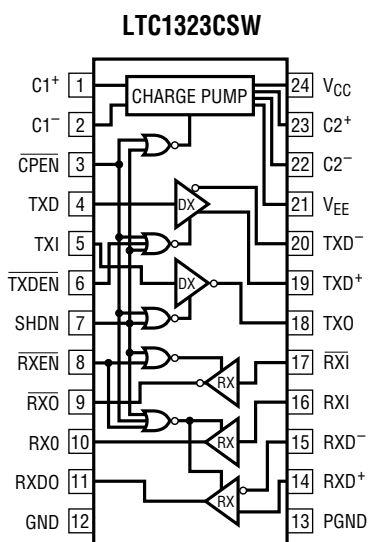
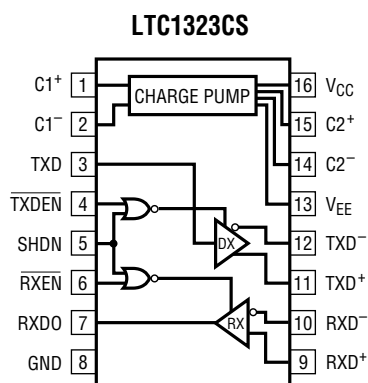
LTC1323 • TPC05

**Single-Ended Driver Swing
vs Temperature**



LTC1323 • TPC06

PIN FUNCTIONS



C1⁺: C1 Positive Input. Connect a 0.33 μ F capacitor between C1⁺ and C1⁻.

C1⁻: C1 Negative Input. Connect a 0.33 μ F capacitor between C1⁺ and C1⁻.

CPEN: TTL Level Charge Pump Enable Input. With $\overline{\text{CPEN}}$ held low, the charge pump is enabled and the chip operates normally. When $\overline{\text{CPEN}}$ is pulled high, the charge pump is disabled as well as both drivers, the noninverting single-ended receiver, and the differential receiver. The inverting single-ended receiver (RXI) is kept alive to monitor the control line and I_{CC} drops to 65 μ A. To turn off the receiver and drop I_{CC} to 0.5 μ A, pull the SHDN pin high.

TXD: Differential Driver Input (TTL compatible).

TXI: Single-Ended Driver Input (TTL compatible).

TXDEN: Differential Driver Output Enable (TTL compatible). A high level on this pin forces the differential driver into three-state; a low level enables the driver. This input does not affect the single-ended driver.

SHDN: Shutdown Input (TTL compatible). When this pin is high, the chip is shut down. All driver and receiver outputs are three-state, the charge pump turns off, and the supply current drops to 0.5 μ A. A low level on this pin allows normal operation.

RXEN: Receiver Enable (TTL compatible). A high level on this pin disables the receivers and three-states the logic outputs; a low level allows normal operation.

RXO: Inverting Single-Ended Receiver Output. Remains active in the receiver keep-alive mode.

RXO: Noninverting Single-Ended Receiver Output.

RXDO: Differential Receiver Output.

GND: Signal Ground. Connect to PGND with 24-pin package.

PGND: Power ground is connected internally to the charge pump and differential driver. Connect to the GND pin.

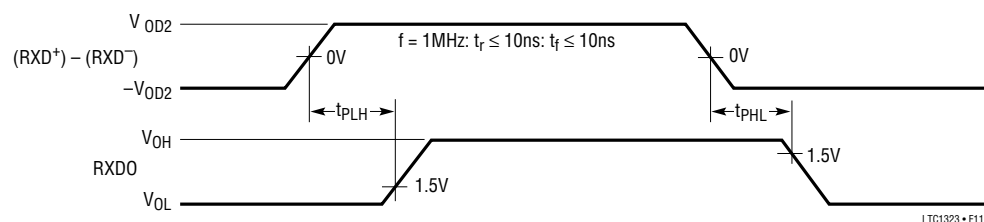
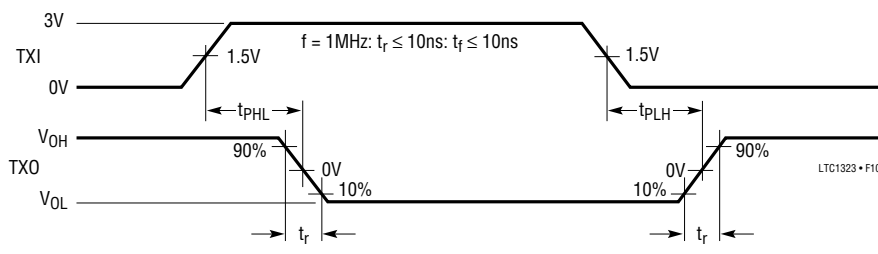
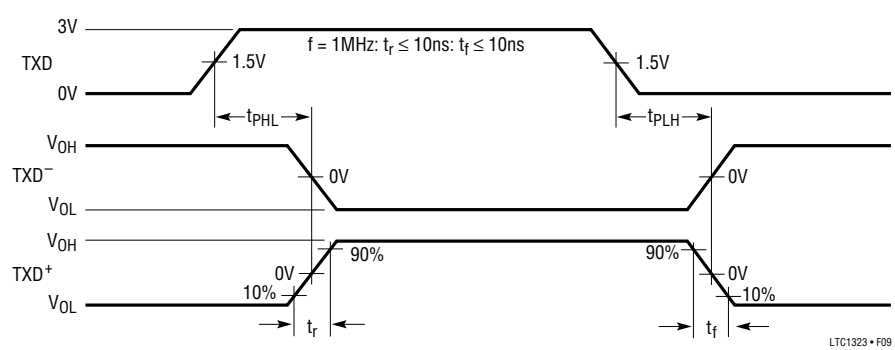
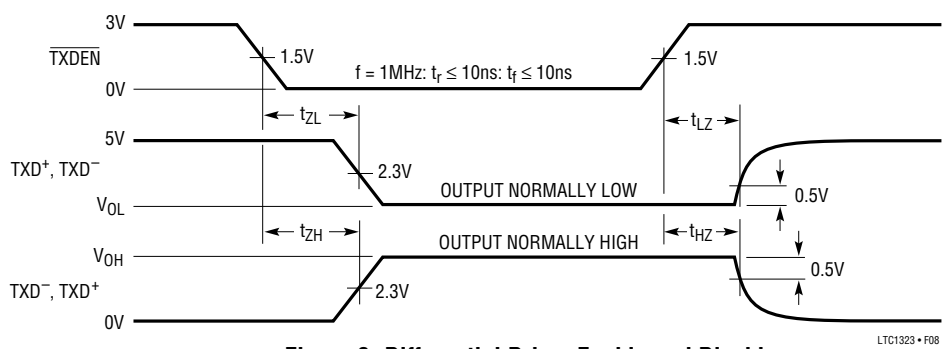
RXD⁺: Differential Receiver Noninverting Input. When this pin is $\geq 200\text{mV}$ above RXD⁻, RXDO will be high; when this pin is $\geq 200\text{mV}$ below RXD⁻, RXDO will be low.

RXD⁻: Differential Receiver Inverting Input.

RXI: Noninverting Receiver Input. This input controls the RXO output.

RXI: Inverting Receiver Input. This input controls the $\overline{\text{RXO}}$ output. In receiver keep-alive mode ($\overline{\text{CPEN}}$ high, SHDN low), this receiver can be used to monitor a wake-up control signal.

SWITCHING WAVEFORMS



APPLICATIONS INFORMATION

Driving Differential AppleTalk or Single-Ended Loads

The differential driver is able to drive either an AppleTalk load or a single-ended load such as a printer or modem. With a differential AppleTalk load, TXD⁺ and TXD⁻ will typically swing between 1.2V and 3.5V (Figure 14a). With a single-ended 3k load such as a printer, either TXD⁺ or TXD⁻ will meet the single-ended voltage swing requirement of $\pm 3.7V$ (Figure 14b). An automatic switching circuit prevents the differential driver from overloading the charge pump if the outputs are shorted to ground while driving single-ended signals. This allows the second single-ended driver to continue to operate normally when the first is shorted, and allows external circuitry attached to the charge pump output to continue to operate even if there are faults at the driver outputs.

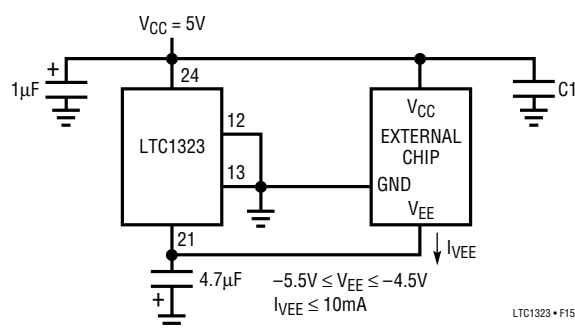


Figure 14

Thermal Shutdown Protection

The LTC1323 includes a thermal shutdown circuit which protects against prolonged shorts at the driver outputs. If a driver output is shorted to another output or to the power supply, the current will be initially limited to a maximum of 500mA. When the die temperature rises above 150°C, the thermal shutdown circuit disables the driver outputs. When the die cools to about 130°C, the outputs are re-enabled. If the short still exists, the part will heat again and the cycle will repeat. This oscillation occurs at about 10Hz and prevents the part from being damaged by excessive power dissipation. When the short is removed, the part will return to normal operation.

Power Shutdown

The power shutdown feature of the LTC1323 is designed for battery-powered systems. When SHDN is forced high the part enters shutdown mode. In shutdown the supply current typically drops from 2.4mA to 0.5μA, the charge pump turns off, and the driver and receiver outputs are three-stated.

Receiver Keep-Alive Mode (24-Pin SO Wide Only)

The 24-pin SO Wide version of the LTC1323 also features a power saving receiver keep-alive mode. When $\overline{CPEN}$ is pulled high the charge pump is turned off and the outputs of both drivers, the noninverting single-ended receiver and the differential receiver are forced into three-state. The inverting single-ended receiver (RXI) is kept alive with I_{CC} dropping to 65μA and the receiver delay time increasing to a maximum of 400ns. The receiver can then be used to monitor a wake-up control signal.

Charge Pump Capacitors and Supply Bypassing

The LTC1323 requires two external 0.33μF capacitors for the charge pump to operate: one from C1⁺ to C1⁻ and one from C2⁺ to C2⁻. These capacitors should be low ESR types and should be mounted as close as possible to the LTC1323. Monolithic ceramic capacitors work well in this application. Do not use capacitors greater than 2μF at the charge pump pins or internal peak currents can rise to destructive levels. The LTC1323 also requires that both VCC and VEE be well bypassed to ensure proper charge pump operation and prevent data errors. A 1μF capacitor from VCC to ground is adequate. A 1μF capacitor is required from VEE to ground and should be increased to 4.7μF if an external load is connected to the VEE pin. Ceramic or tantalum capacitors are adequate for power supply bypassing; aluminum electrolytic capacitors should only be used if their ESR is low enough for proper charge pump operation. Inadequate bypass or charge pump capacitors will cause the charge pump output to go out of regulation prematurely, degrading the output swing at the SINGLE-ENDED driver outputs.

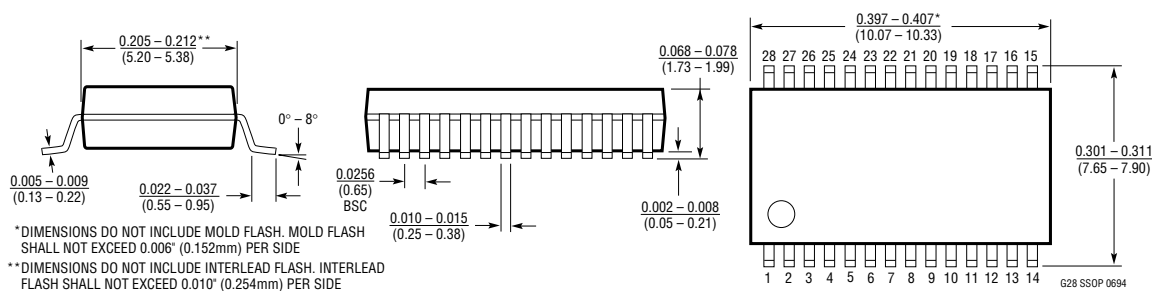
PACKAGE DESCRIPTION

Dimensions in inches (millimeters) unless otherwise noted.

G Package

28-Lead Plastic SSOP (0.209)

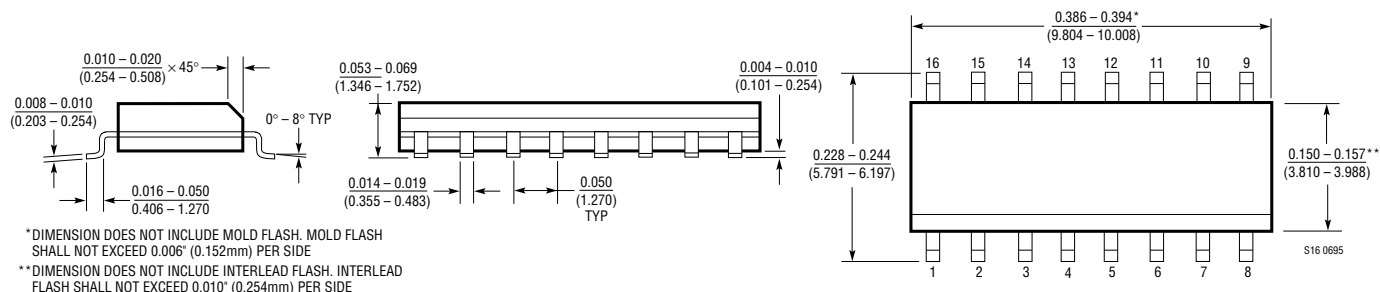
(LTC DWG # 05-08-1640)



S Package

16-Lead Plastic Small Outline (Narrow 0.150)

(LTC DWG # 05-08-1610)



SW Package

24-Lead Plastic Small Outline (Wide 0.300)

(LTC DWG # 05-08-1620)

